

July 2014
Sheridan School Bond Update

Bond Update

- On June 30th a meeting was conducted by District Project Manager to tour the High School and Chapman School to discuss the scope of improvements in Security and I/T infrastructure requested at this time. In attendance were District representatives from technology Department, Facilities, School principals, District Superintendent, two representatives from Point Monitor Security and DAY CPM Project Manager. We toured the facilities and learned the current issues in security functionality at both facilities. There also was discussion on the desired improvements in hardware and software to meet the current requirements of the Sheridan School District.
- Currently, there is final work being done on defining the scope of the work to accurately reflect what was discussed in that meeting. There will be invitations to bid sent to three firms to offers quotations on this work.
- We expect bid results by July 25th.

Bond Update Continued

- We are working closely with the Cascade Technology Alliance to identify the type of servers required and they will program the servers for us. We have identified the number of wireless access points and switches required for the high school and will order soon.

Bond Update Continued

- We have been working with Piper Jaffray to get the paper work completed for the district ratings for the bond sales we are expecting to maintain our A+ bond rating. We expect to receive our rating on July 30.
- In your packet for this meeting you also have the preliminary official statement we have two weeks to review the document and then it will be final on July 31.